

Abstract

APPARATUS FOR PROCESSING WAFERS

Systems and methods are described for wafer processing. A wafer processing
5 apparatus includes: a first wafer transporter, a process station coupled to the first
wafer transporter, the process station including: a first plurality of wafer processing
stacks, each of the plurality of wafer processing stacks including a plurality of wafer
processing modules, and a second wafer transporter coupled to the plurality of wafer
processing modules, each of the plurality of wafer processing modules adjacent, and
10 accessible by, the second wafer transporter, and a third wafer transporter coupled to
the process station, wherein any of the plurality of wafer processing modules in any
of the plurality of wafer processing stacks can be accessed by at least two adjacent
wafer transporters from among the first, second and third wafer transporter. The
systems and methods provide advantages from minimizing pre-process and/or post-
15 process times, minimizing variation of the pre-process and/or post-process times and
reducing robot over utilization.

Fig. 4



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